

## 产品规格书/Specification

|                 |                 |
|-----------------|-----------------|
| 产品/product:     | 填孔钯浆料/ Pd paste |
| 料号/Part number: | 60H-5901        |

### 适用范围/Application:

适用于高温厚膜电路、LTCC 陶瓷，叠层元件填孔导通电极使用

Suitable for high-temperature thick film circuits, LTCC ceramics, and laminated component via filling and conductive electrodes.

### 使用条件/Operating conditions:

|                               |   |
|-------------------------------|---|
| 基材<br>Substrate               | 氧化铝陶瓷，LTCC 陶瓷，叠层元件<br>Alumina ceramic   |
| 印刷<br>Printing                | 200-300 目丝网印刷<br>200-300 mesh stainless screen  |
| 干燥&烧结<br>Drying<br>&Sintering | ① 单层印刷（氧化铝板）<br>Single layer printing(Alumina ceramic)<br>通风烘箱烘烤 100-150°C，10-15 分钟<br>100-150°C 10-15 min<br>空气下烧结，峰值 850°C（最低推荐值），2-10 小时。<br>(可根据实际需要调高烧结温度 850~1400°C)<br>Sintering in air with a peak temperature of 850°C (minimum recommended value) for 2 to 10 hours. (The sintering temperature can be adjusted upward according to actual needs from 850°C to 1400°C.) |
|                               | ② 多层印刷<br>Multilayer printing<br>200-500°C温度间排胶，最少 60 分钟<br>Binder removing, 200-500°C, 60 mins at least<br>空气下烧结，峰值 850°C（最低推荐值），2-10 小时。<br>(可根据实际需要调高烧结温度 850~1400°C)<br>Sintering in air with a peak temperature of 850°C (minimum recommended value) for 2 to 10 hours. (The sintering temperature can be adjusted upward according to actual needs from 850°C to 1400°C.)   |
| Thinner                       | ST-1000   |

**性能/Characteristics:**

**1. 浆料性能/Paste Characteristics:**

| 性能<br>Characteristic | 标准<br>Standard | 测试方法及条件<br>Test method and conditions  |
|----------------------|----------------|--|
| 1 Fineness           | ≤5μm           | FOG test   |
| 2 Viscosity          | 280-530Pa.s    | Brookfield HBT utility cup and spindle (SC4-14/6R), 10rpm, 25±1°C,<br>Brookfield HBT (博利飞) 粘度计, 转子 SC4-14/6R), 10rpm, 25±1°C<br>粘度可根据用户实际需要调节。 |

**2. 烧结后特性/Characteristics after firing:**

在 1 烧结条件下, 膜厚 8-12μm Check fired film produced under the conditions specified in 1), (Film thickness is 8-12μm.)

| 特性<br>Characteristics         | Standard<br>标准 | 测试方法和条件<br>Test method and conditions   |
|-------------------------------|----------------|---|
| 3 Resistivity<br>方阻           | ≤80mΩ/<br>□    | Test pattern 0.6mm×60mm<br>测试图形 0.6mm×60mm  |
| 4 Adhesion<br>strength<br>附着力 |                | Peel Test: 0.5mmφ Tin plated Cu wire soldered on 2mm×2mm Pad.<br>0.5mmφ锡浸铜线, 焊接面积 2mm×2mm<br>Solder: 96.5Sn/0.5Cu Mildly activated flux used. |
| Initial<br>初始附着力              | ≥33.2N         | 焊料: 96.5Sn/0.5Cu  |

**保存条件, 有效期/Storage condition and Term of validity**

产品应在 5-25°C 的环境温度下密封储存, 有效期为产品发货之日起 1 年。

The product shall be guaranteed for 1 year after shipping date, keep tightly under at 5-25°C

**包装方式/Packaging method:**

标准包装, 1000g/罐, 样品可提供 200 克小罐包装

Standard package 1000g/can, if you need sample to test, available 200g with small package.